

### 100mm (4.0INCH) SINGLE DIGIT NUMERIC DISPLAY

Blue



ATTENTION
OBSERVE PRECAUTIONS
FOR HANDLING
ELECTROSTATIC
DISCHARGE
SENSITIVE
DEVICES

Part Number: SA40-19QBWA-D

#### **Features**

- Large size.
- 4.0 inch digit height.
- Low current operation.
- Excellent character appearance.
- High light output.
- Easy mounting on P.C. boards or sockets.
- Mechanically rugged.
- Standard : gray face, white segment.
- RoHS compliant.

### **Description**

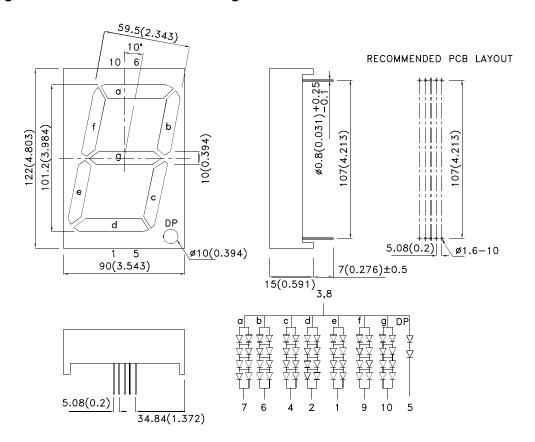
The Blue source color devices are made with InGaN Light Emitting Diode.

Static electricity and surge damage the LEDS.

It is recommended to use a wrist band or anti-electrostatic glove when handling the LEDs.

All devices, equipment and machinery must be electrically grounded.

### Package Dimensions& Internal Circuit Diagram



#### Notes

1. All dimensions are in millimeters (inches), Tolerance is ±0.25(0.01")unless otherwise noted.

2. The specifications, characteristics and technical data described in the datasheet are subject to change without prior notice.





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### **Selection Guide**

Part No.	Dice	Lens Type	lv (uc @ 10	,	Description
			Min.	Тур.	
SA40-19QBWA-D	Blue (InGaN)	White Diffused	31000	68000	Common Anode, Rt. Hand Decimal.

#### Notes:

- 1. Luminous intensity/ luminous Flux: +/-15%.
  2.Luminous intensity value is traceable to the CIE127-2007 compliant national standards.

### Electrical / Optical Characteristics at TA=25°C

Symbol	Parameter	Device	Тур.	Max.	Units	Test Conditions
λpeak	Peak Wavelength	Blue	460		nm	I=20mA
λD [1]	Dominant Wavelength	Blue	465		nm	I=20mA
Δλ1/2	Spectral Line Half-width	Blue	25		nm	IF=20mA
С	Capacitance	Blue	100		pF	VF=0V;f=1MHz
VF [2]	Forward Voltage Per Segment Or (DP)	Blue	13.2 (6.6)	16 (8)	V	I=20mA
lr	Reverse Current Per Segment Or (DP)	Blue		100 50	uA	V <sub>R</sub> =5V (V <sub>R</sub> =5V)

- Navelength: +/-1nm.
   Forward Voltage: +/-0.1V.
   Wavelength value is traceable to the CIE127-2007 compliant national standards.

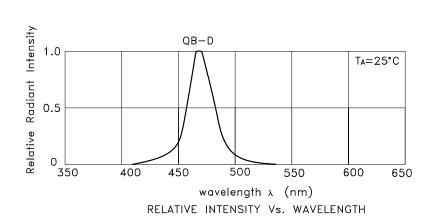
Absolute Maximum Ratings at TA=25°C

Parameter	Blue	Units	
Power dissipation Per Segment Or (DP)	480 (240)	mW	
DC Forward Current Per Segment Or (DP)	30 (30)	mA	
Peak Forward Current [1] Per Segment Or (DP)	150 (150)	mA	
Reverse Voltage Per Segment Or (DP)	5 (5)	V	
Operating / Storage Temperature	-40°C To +85°C		
Lead Solder Temperature[2]	260°C For 3-5 Seconds		

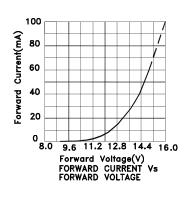
### Notes:

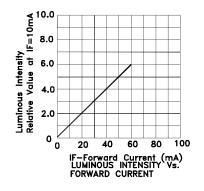
- 1. 1/10 Duty Cycle, 0.1ms Pulse Width.
   2. 2mm below package base.

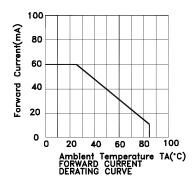
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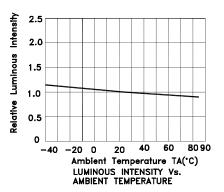


Blue SA40-19QBWA-D





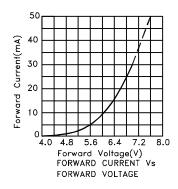


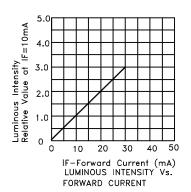


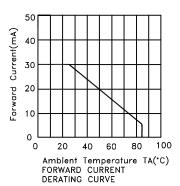
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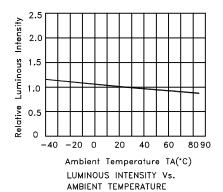
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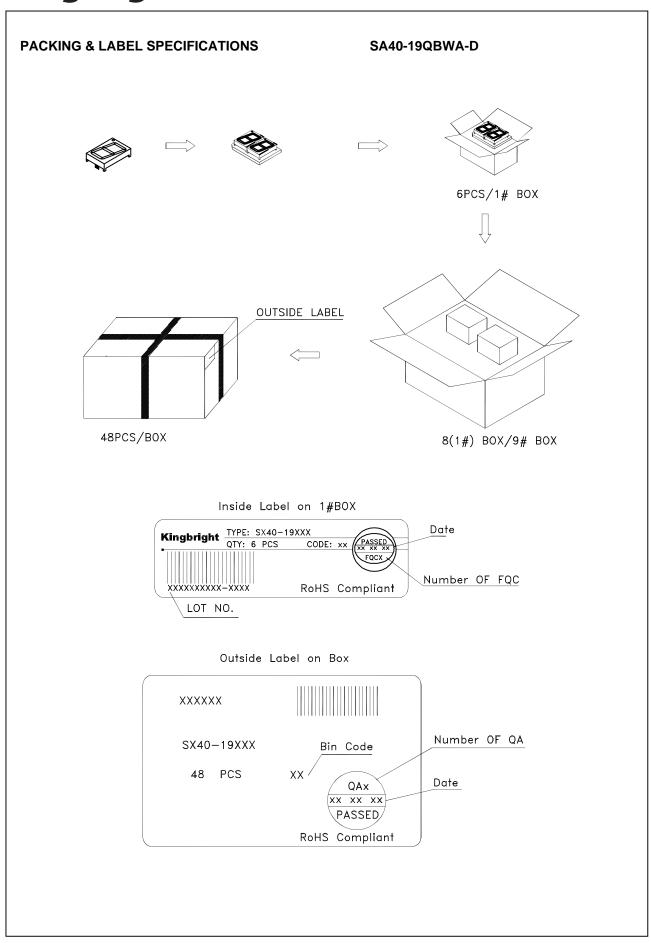








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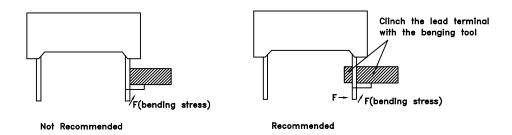


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### THROUGH HOLE DISPLAY MOUNTING METHOD

### Lead Forming

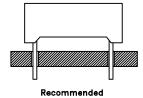
Do not bend the component leads by hand without proper tools. The leads should be bent by clinching the upper part of the lead firmly such that the bending force is not exerted on the plastic body.



### Installation

- 1. The installation process should not apply stress to the lead terminals.
- 2. When inserting for assembly, ensure the terminal pitch matches the substrate board's hole pitch to prevent spreading or pinching the lead terminals.





3. The component shall be placed at least 5mm from edge of PCB to avoid damage caused excessive heat during wave soldering.

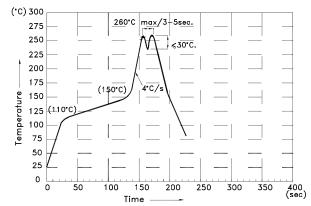




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### DISPLAY SOLDERING CONDITIONS

Wave Soldering Profile For Lead-free Through-hole LED.



#### NOTES:

- 1.Recommend the wave temperature 245°C $\sim$ 260°C.The maximum soldering temperature should be less than 260°C.
- $2.\mbox{Do}$  not apply stress on epoxy resins when temperature is over 85°C.
- 3. The soldering profile apply to the lead free soldering (Sn/Cu/Ag alloy).
- 4.During wave soldering , the PCB top-surface temperature should be kept below 105°C 5 No more than once

### Soldering General Notes:

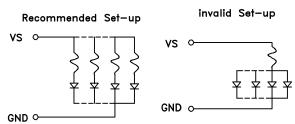
- 1. Through—hole displays are incompatible with reflow soldering.
- 2. If components will undergo multiple soldering processes, or other processes where the components may be subjected to intense heat, please check with Kingbright for compatibility.

#### **CLEANING**

- 1.Mild "no-clean" fluxes are recommended for use in soldering.
- 2. If cleaning is required, Kingbright recommends to wash components with water only. Do not use harsh organic solvents for cleaning, because they may damage the plastic parts .And the devices should not be washed for more than one minute.

### CIRCUIT DESIGN NOTES

- 1.Protective current-limiting resistors may be necessary to operate the Displays.
- 2.LEDs mounted in parallel should each be placed in series with its own current—limiting resistor.



Detailed application notes are listed on our website. <a href="http://www.kingbright.com/application">http://www.kingbright.com/application</a> notes

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